Customer View Model

3D_IGS.ZIP

English

Customer View Model

3D_STP.ZIP

English

FEATURES

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Please review product documents or contact us for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

Sleeve Style Closed Bottom
Connector System Cable-to-Board
Sealable No
Connector & Contact Terminates To Printed Circuit Board
Product Type Contact
Profile Zero
Wire/Cable Type Discrete Wire

Body Features

Sealant Without
Sleeve Plating Material Tin
Sleeve Material Copper

Contact Features

Contact Current Rating (Max) (A) 7.5
Contact Type Socket
Contact Spring Plating Thickness .762 µm [30 µin]
Contact Spring Plating Material Gold
Contact Mating Area Plating Thickness 30 µm [30 µin]
Contact Transmits (Typical) Signal (Data)/Power
Contact Base Material Beryllium Copper
Socket Type Discrete

Termination Features

Termination Method to PC Board Through Hole - Press-Fit
Termination Method to Wire/Cable Solder
Insertion Method Hand/Semi-Automatic

Dimensions

Socket Length 6.6 mm [.26 in]
Hole Size (Recommended) 1.83 mm [.072 in]
Wire/Cable Size .518 – .823 mm² [20 – 18 AWG]
Mating Pin Diameter Range .86 – 1.04 mm [.034 – .041 in]
PCB Thickness (Recommended) .79 – 3.18 mm [.031 – .125 in]

Usage Conditions

Operating Temperature Range -65 – 125 °C [-85 – 257 °F]

Operation/Application

Circuit Application Power, Signal

Packaging Features

Packaging Method Bag, Loose Piece
Packaging Quantity 2000

Other

Spring Material Beryllium Copper

PRODUCT COMPLIANCE

Statement of Compliance

Statement of Compliance
PDF